

1-2102061-1 ✓ ACTIVE

Mezalok | AMP Mezalok

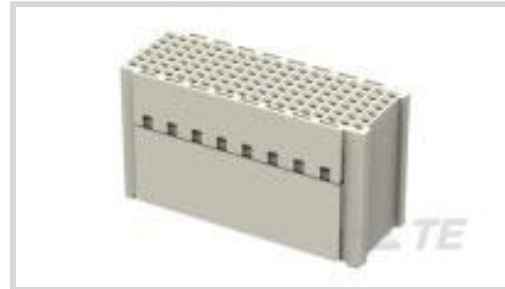
TE Internal #: 1-2102061-1

PCB Mount Receptacle, Vertical, Board-to-Board, 114 Position, 1.27 mm [.05 in] Centerline, Gold, Surface Mount - Solder Ball, Signal, AMP Mezalok

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **114**

Number of Rows: **6**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	114
Number of Rows	6
Board-to-Board Configuration	Parallel

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	750 VAC
Operating Voltage	250 VAC

Body Features

Primary Product Color	Natural
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Contact Features

Contact Layout	Matrix
Mating Tab Width	.43 mm[.017 in]



Mating Tab Thickness	.46 mm[.018 in]
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Bright
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Beryllium Copper
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm [29.9212 μin]
Contact Type	Socket
Contact Current Rating (Max)	1.5 A

Termination Features

Termination Method to Printed Circuit Board	Surface Mount - Solder Ball
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Mechanical Attachment

PCB Mount Alignment Type	None
PCB Mount Retention Type	Solder Ball
Mating Alignment	With
Mating Alignment Type	Polarizing Tab
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

Housing Features

Mating Entry Location	Top
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP (Liquid Crystal Polymer)

Dimensions

Connector Height	14 mm[.55 in]
Row-to-Row Spacing	1.27 mm[.05 in]
Stack Height	18 mm[.709 in]
PCB Thickness (Recommended)	2.36 mm[.093 in]

Usage Conditions

Operating Temperature Range	-55 – 125 $^{\circ}\text{C}$ [-67 – 257 $^{\circ}\text{F}$]
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Operation/Application



Assembly Process Feature	Pick and Place Cover
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Circuit Application	Signal
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Industry Standards

Industry Standard	VITA 61
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Packaging Features

Packaging Quantity	100
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Packaging Type	Tape & Reel
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	<p>Current ECHA Candidate List: JUNE 2022 (224)</p> <p>Candidate List Declared Against: JAN 2022 (223)</p> <p>SVHC > Threshold:</p> <p>Pb (36.09% in Component Part)</p> <p>Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.</p>
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Reflow solder capable to 260°C
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Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | AMP Mezalok



Documents

Product Drawings

[Mezalok, Socket, 114 p, 18 mm, 30 Au, TL](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1-2102061-1_K.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2102061-1_K.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2102061-1_K.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[SOSA Aligned Interconnect Solutions](#)

English

[Mezalok Connector Brochure](#)

English

Product Specifications

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Product Specification

English